

CLAIM AMENDMENT

1. (Currently Amended) A through hole conduction structure of a flexible multilayer circuit board, comprising: an internal layer circuit board ~~which can be a eable portion;~~ having a wiring pattern and an external layer circuit board ~~which can be a component mounting portion~~ laminated on one side or both sides of said internal layer circuit board ~~at a predetermined position, wherein, in said flexible multilayer circuit board having~~ a through hole plated conduction portion formed ~~at predetermined positions of in~~ said internal layer circuit board and said external layer circuit board, a surface protection layer formed on an external surface of a the wiring pattern of, said surface protection layer having a retreated portion which is outwardly retreated from the outside edge of the through hole of ~~said internal layer circuit board is formed in a region retreated toward the outside from a position of a through hole for the through hole plated conduction portion.~~

2. (Original) The through hole conduction structure of a flexible multilayer circuit board according to claim 1, wherein said surface protection layer is a cover film consisting of polyimide resin.

3. (Currently Amended) A method for forming a through hole conduction structure of a flexible multilayer circuit board comprising the steps of: forming a required wiring pattern on one side or both sides of a flexible insulating base material; preparing an internal layer circuit board having a surface protection layer formed thereto on an external surface of said wiring pattern at a position retreated toward the outside from a position where a ~~predetermined~~ through hole is to be formed; laminating an external layer circuit board ~~which can be a component mounting portion~~ on one side or both sides of said internal layer circuit board in association with a position of said internal layer circuit board

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where said through hole is formed; forming a through hole ~~at predetermined positions of~~ in said internal layer circuit board and said external layer circuit board; and then forming a through hole plated conduction portion on an inner surface of said through hole.

4. (Original) The method for forming a through hole conduction structure of a flexible multilayer circuit board according to claim 3, wherein a cover film consisting of polyimide resin is used for said surface protection layer.

5. (New) A through hole conduction structure of a flexible multilayer circuit board according to claim 1, wherein a diameter of the through hole and a diameter of the outwardly retreated portion is about a 1 to 2.3 ratio.

6. (New) A through hole conduction structure of a flexible multilayer circuit board according to claim 5, wherein the diameter of the through hole is about 0.3 mm and the diameter of the outwardly retreated portion is about 0.7 mm.